

IEEE 1149.4 Mixed-Signal Test Bus Working Group Meeting Minutes

for

March 11th, 2008
8:00 – 9:00 AM

Meeting Agenda:

Time	Topic	Responsibility
8:00 – 9:00 AM	1. Review meeting minutes for Feb. 26 th , 2008	All
	2. Update on ABSDL parser development	All
	3. Review standard documentation	All
	4. Other issues.	All
9:00 AM	Meeting adjourned	Bambang

Meeting Attendees:

Name	Company
Adam Ley	Asset-Intertech
Ken Parker	Agilent Technologies
Heiko Ehrenberg	Goepel Electronics LLC
Adam Cron	Synopsys
Zafar Quadri	Flextronics
Bruce Kim	University of Alabama
Bambang Suparjo	Mentor Graphics

1. Review meeting minutes for February 26th, 2008.

- a. For minute 3a, Adam Ley commented that the issue related to non-test pin is not only on its definition but also the effect of this permission to the existing documented ABM applications and BSDL extensions.
- b. The meeting minutes for February 26th, 2008 have been approved with correction in minute 3a, suggested by Adam Ley and seconded by Ken.

2. Update on ABSDL parser development

Bambang has not been able to forward the parser to the TI group. He will package together with the updated BSDL file for STA400.

3. Review Standard Draft

- a. Proposal on Permission 7.3.1.3 - An ABM may be connected to any non-test pin.

The introduction of this permission requires an effort to review the existing ABM applications in interconnect test measurements. As an example, when an ABM is inserted at power pin or ground pin, the voltage drop across the ABM needs to be taken into account in the measurement.

Also the behavior of an ABM that attached to a non-test pin is not able to be described in BSDL.

Based on the above reasons, for now, the group decided to drop this permission proposal. A note regarding the ABM behavior cannot be described in BSDL when the module is attached to a non-test pin will be added in the BSDL documentation (10.4).

- b. Issue on Rcom

Adam Cron proposed a new single diagram as shown in the Appendix, based on the original diagram and the detail Rcom information/diagram provided by Ken.

The Rcom element has been simplified. Adam Ley was requesting a clarification on R_{S1} and R_{S2} . According to Adam Cron, both R_{S1} and R_{S2} are from the two R_S resistors in the original diagram. Although after reviewing the diagram and the description in 9.3.2, there are few things that require more clarification regarding R_S and the resistance due to the protection circuitry. The group suggested that Steve Sunter should be invited to join the next teleconference to discuss this issue.

- c. The other items in the review list were not able to be discussed in this teleconference due to the limited time.

4. Other issues

- a. The tentative date for the next meeting is March 28th, 2008 at 8 AM PDT. Bambang will confirm the date after contacting Steve Sunter.
- b. Adam Cron will provide the private area access information to Bruce Kim.

5. The meeting adjourned at 9:00 AM PDT

Appendix – Diagram for Figure 39

a. Original diagram as in version 1999

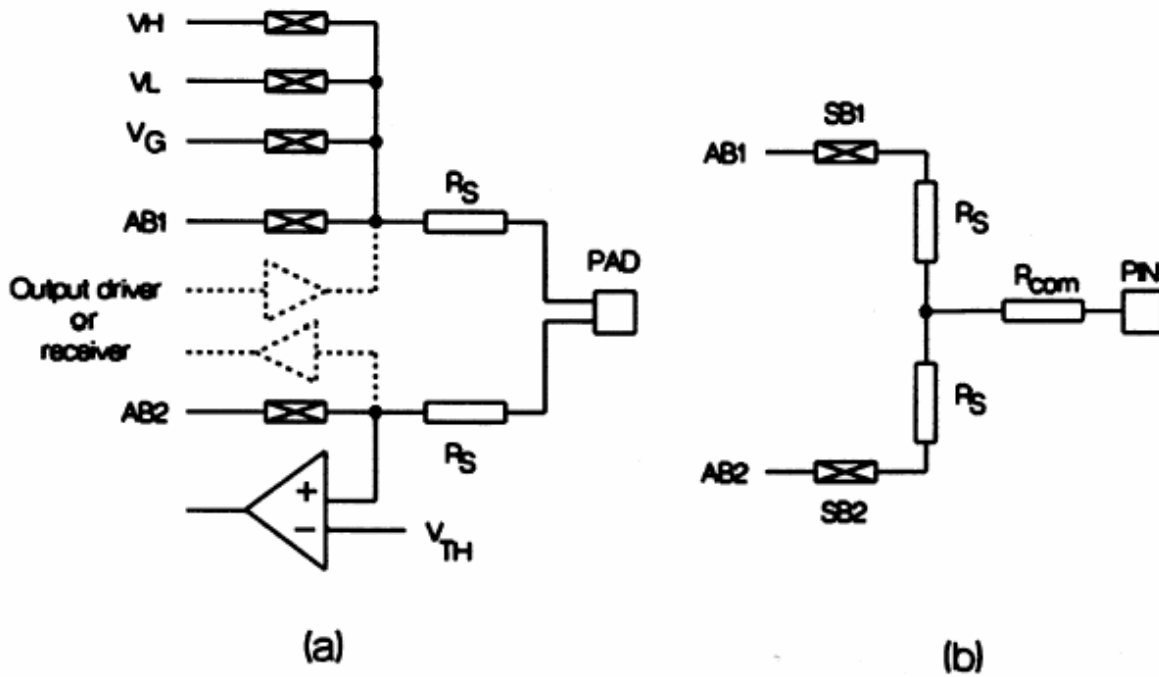
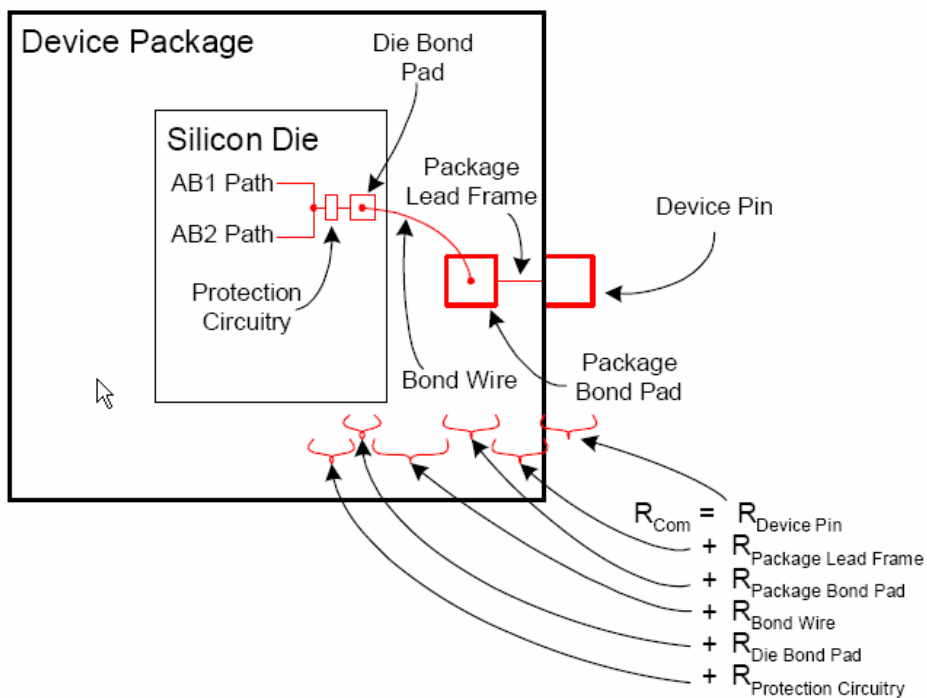


Figure 39—Switch connections to bonding pads

b. Rcom diagram/information from Ken



c. Updated diagram proposed by Adam Cron

